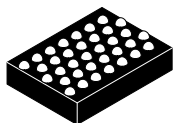


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

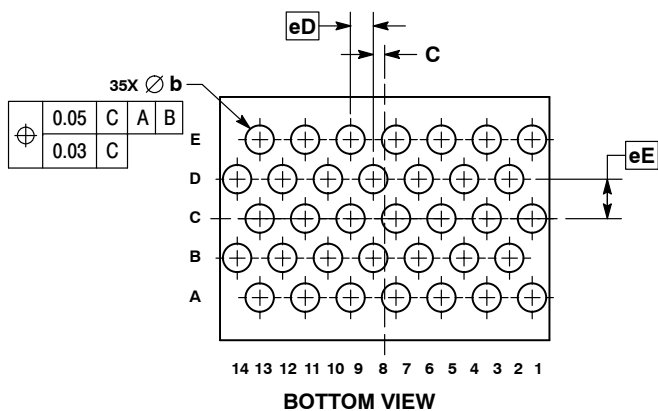
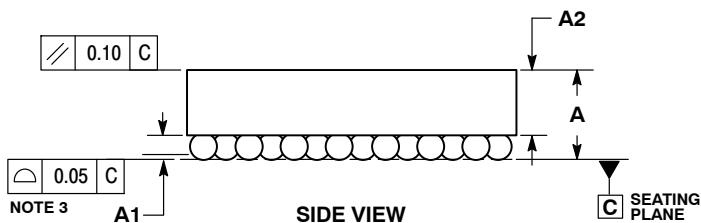
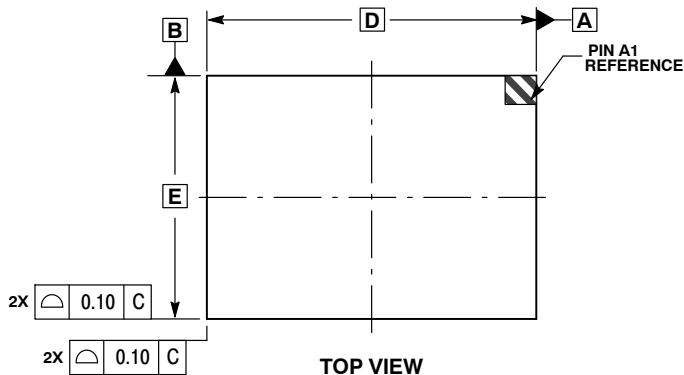
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SCALE 4:1

WLCSP35, 3.63x2.68  
CASE 567AG-01  
ISSUE B

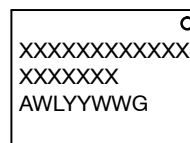
DATE 24 JAN 2011



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.84	1.00
A1	0.17	0.23
A2	0.72 REF	
b	0.24	0.29
C	0.125 BSC	
D	3.63 BSC	
E	2.68 BSC	
eD	0.25 BSC	
eE	0.433 BSC	

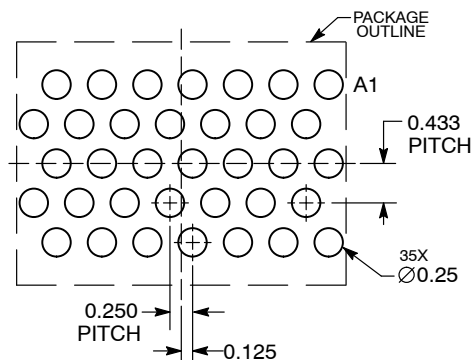
### GENERIC MARKING DIAGRAM\*



- XXXXXX = Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.

### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP35, 3.63X2.68	PAGE 1 OF 1

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